This issue of the Advanced Packaging Update features special coverage of large area panel fan-out wafer level packaging (FO-WLP) developments. The panel market is divided into high-density RDL (≤2µm L/S with multiple RDLs) versus low-density (>5µm L/S with ≤3 RDLs). Panel activities at major organizations are discussed and a market forecast for low-density panels is included. High-performance packaging options including silicon interposers and alternatives such as fan-out on substrate are presented. A special section examines developments in electro-magnetic interference (EMI) shielding. Huawei’s new 5G smartphone is examined. Outsourced semiconductor assembly and test (OSAT) financials are analyzed.

Table of Contents
1 Industry and Economic Trends
  1.1 Macroeconomic Trends
  1.2 Trade Tensions Continue
    1.2.1 U.S. and China Conflict
    1.2.2 Huawei’s Smartphones
      1.2.2.1 Packages in Mate 30 5G
      1.2.2.2 Comparison with Mate 20X 5G
    1.2.3 Japan and South Korea Conflict
  1.3 Semiconductor Sector
2 OSAT Financial Analysis
  2.1 Definitions
  2.2 OSAT Market Performance
  2.3 Outlook
3 Fan-Out Panel Developments
  3.1 Panel Drivers
  3.2 Panel Applications
    3.2.1 Application Processor and PMIC
    3.2.2 Image Sensor
    3.2.3 Memory
    3.2.4 Antenna-in-Package for 5G
  3.3 Challenges for Panel Production
  3.4 Company Activities
    Amkor, ASE, China Wafer Level CSP, Nepes, PTI, Samsung, Unimicron
  3.5 Research Consortia
    ASM Pacific’s FOP-WLP Consortium, Fraunhofer IZM, IME A*STAR, iNEMI, JOINT Consortium, NCAP
  3.6 FO Panel Capacity and Market Forecast
4 High-Performance Package Trends
  4.1 Package Trade-offs
    4.1.1 Amkor Technology
    4.1.2 ASE
    4.1.3 TSMC’s High-Density Options
    4.1.4 TSMC’s Organic RDL Interposer
    4.1.5 High-Density FO and Si Interposer Forecast
5 EMI Shielding
  5.1 EMI Shielding in Smartphones
2019 BGA and CSP Bibliography
References
List of Figures
1.1 Monthly U.S. housing starts.
2.1 Quarterly revenue for top 20 OSATs.
3.1 Mold-first FOPLP process flows.
3.2 Samsung’s smartwatch module.
3.3 FO-WLP for image sensor.
4.1 Polymide stress contours of the RDL.
4.2 Normalized polyimide stress on RDLs.
List of Tables
1.1 Mate 30 5G Package Types
1.2 Mate 30 5G Package Examples
1.3 Mate 20X 5G and Mate 30 5G Comparison
3.1 Panel Economics Depends on Package Size
3.2 Samsung Galaxy Watch Module Measurements
3.3 FO-WLP Panel Activities
3.4 RDL Interposer Panel Activities
3.5 PTI’s Panel Fan-Out WLP Options
3.6 FO-WLP Panel Consortia
3.7 Forecast for Low-Density Panel Demand
3.8 Estimated Annual Low-Density Panel Capacity
4.1 High-Density Package Performance Metrics
4.2 3D SoC for Logic + Memory Integration
4.3 Markets for Si Interposer and HPC HD FO
5.1 iPhone 11 Pro Max and Conformal Shielding